Next Generation Photonic Integration and Packaging Solutions with **Photonic Wire Bonding (PWB)** and **Facet-Attached Micro-Optical Elements**

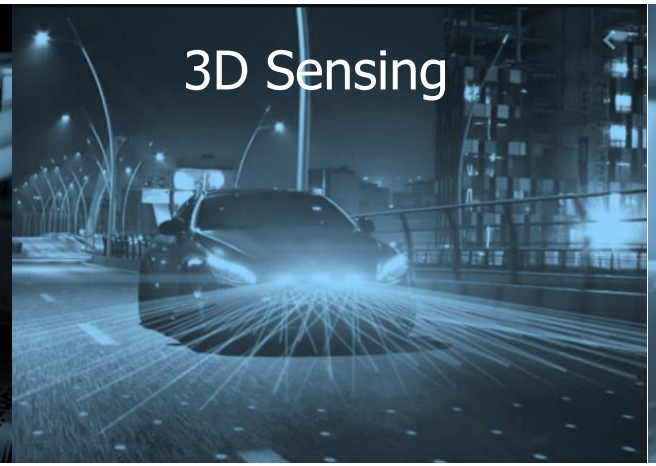
Dr. Zewang You

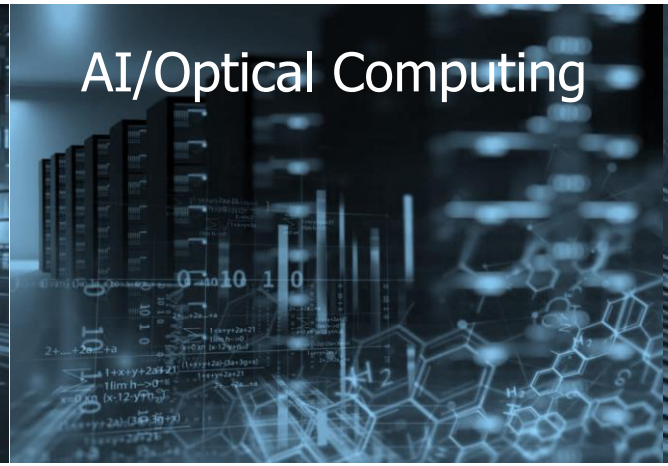
CIOE 2024-09-11, Shenzhen

vanguard AUTOMATION

MYCRONIC

Photonic Integrated Circuits are Growing Rapidly





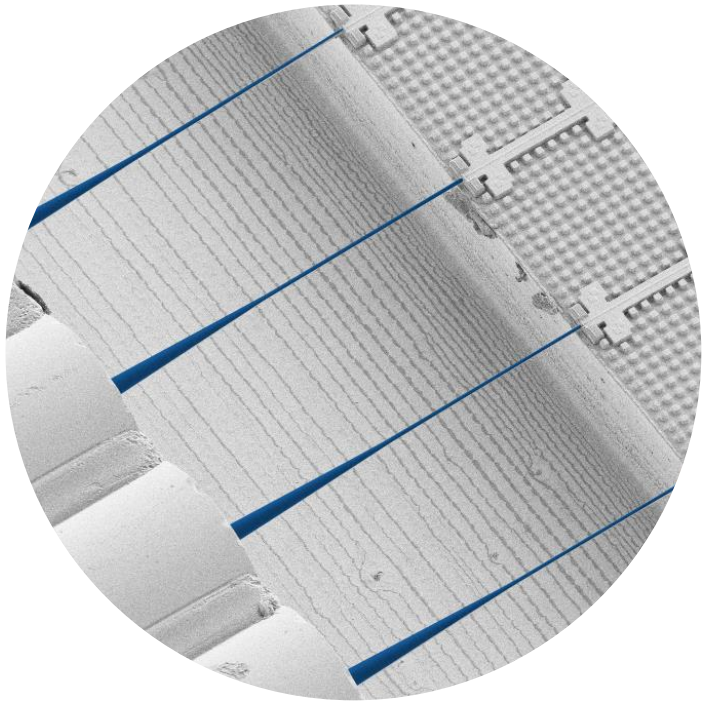
Our Mission

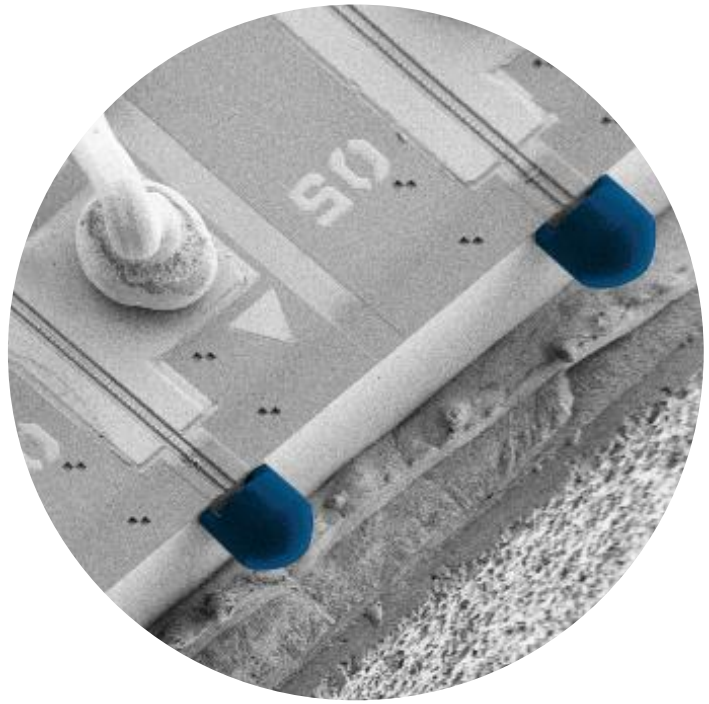
Advance Photonic Packaging and Assembly by providing scalable 3D nano-fabrication solutions for prototyping and manufacturing

vanguard AUTOMATION

MYCRONIC

Enabling Next Generation **Photonic Integration and Packaging** Solutions with **3D Laser Lithography Solutions**



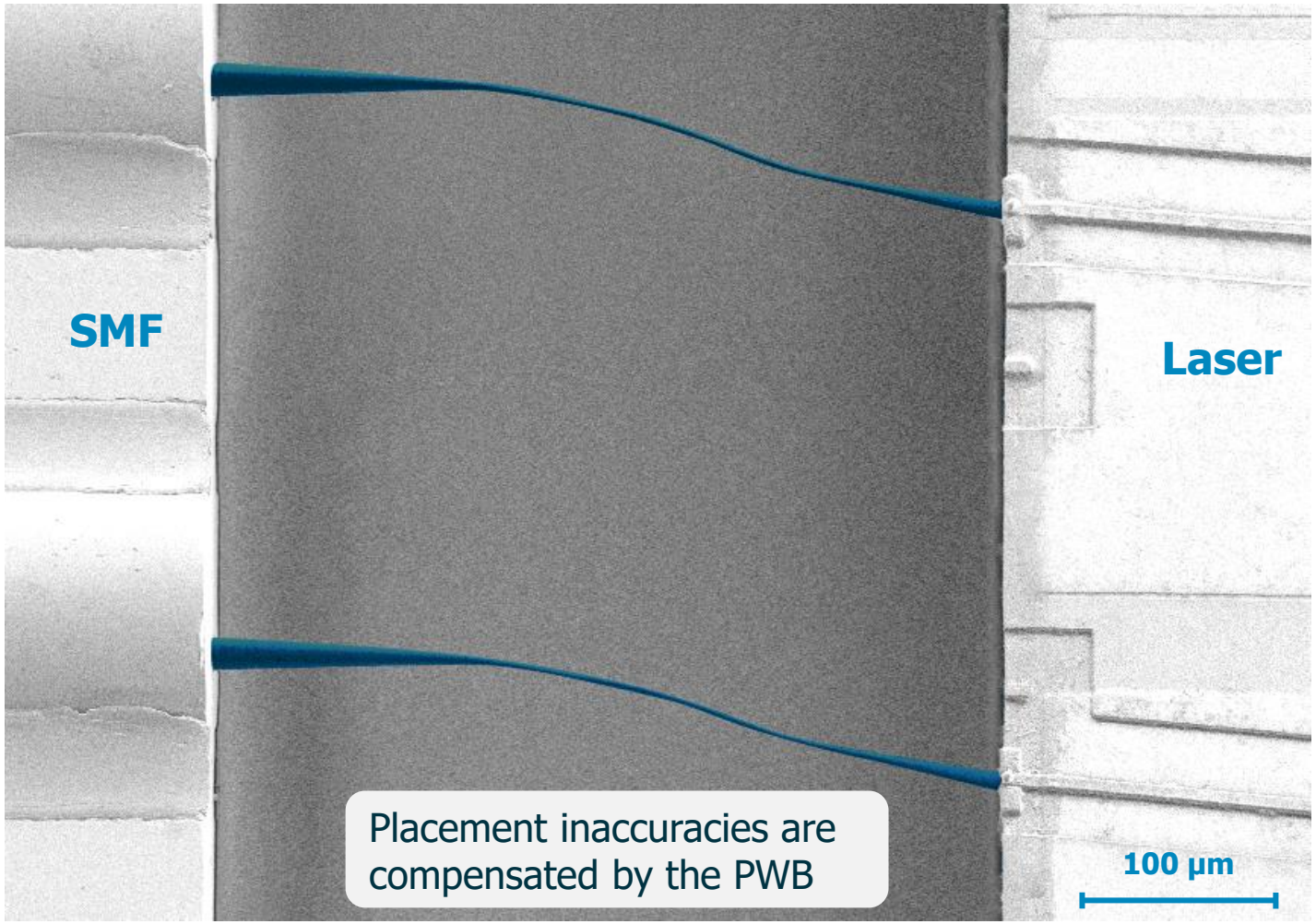


Photonic Wire Bonding (PWB) and **Facet-Attached Micro-Optical Lenses (FAML)**

vanguard AUTOMATION

MYCRONIC

Photonic Wire Bonding: The Benefits



Laser by Freedom Photonics LLC

Low loss connection to arbitrary mode fields

Automated, **reproducible** and **fast** processes

Reliable connections under various conditions

High interconnect density (compact modules)

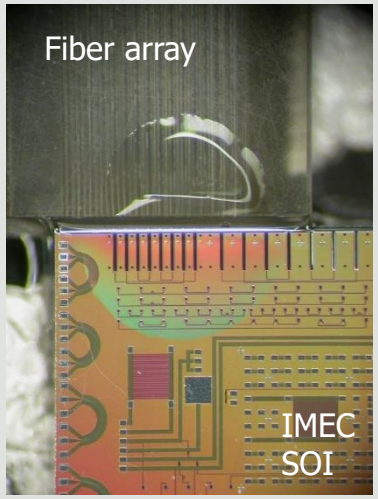
High degree of **design flexibility** for hybrid multi-chip integration

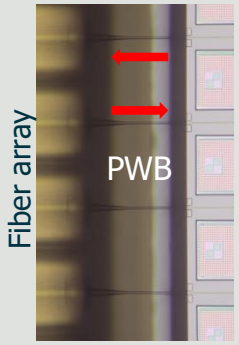
vanguard AUTOMATION
MYCRONIC

Compatibility with material platforms/foundries

Silicon (**IMEC**, Belgium)

- **~2dB Loss**



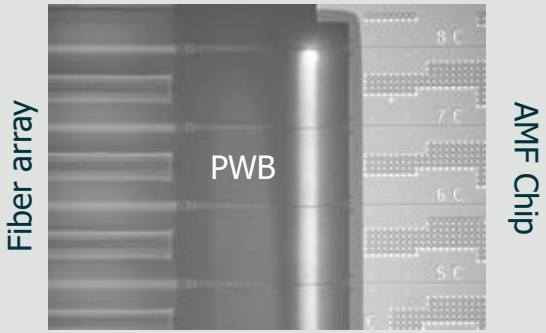


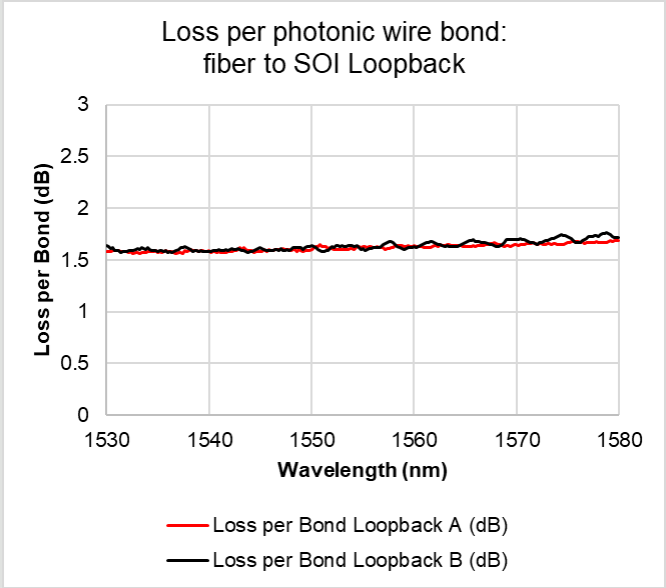
Building-block of

PIXAPP
Photonic Packaging
Pilot Line

Silicon (**AMF**, Singapore)

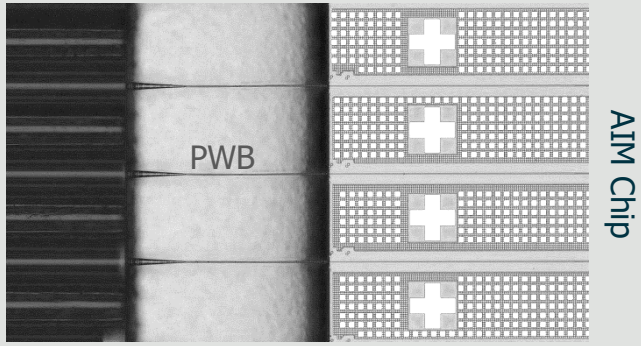
- **~1.5dB loss**

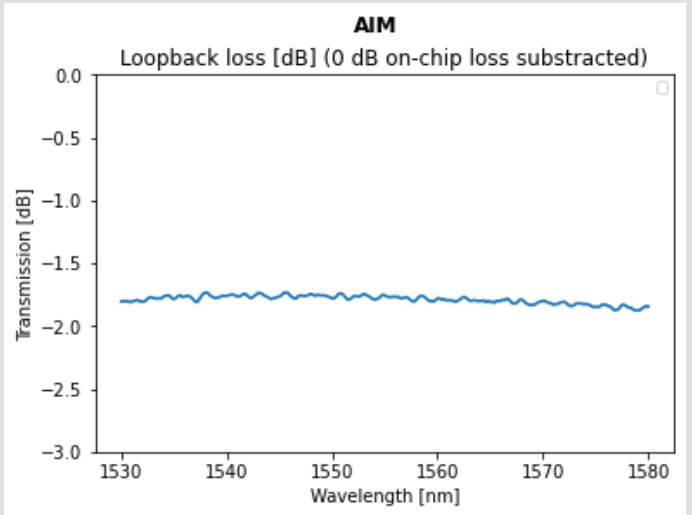




Silicon Nitride (**AIM**, USA)

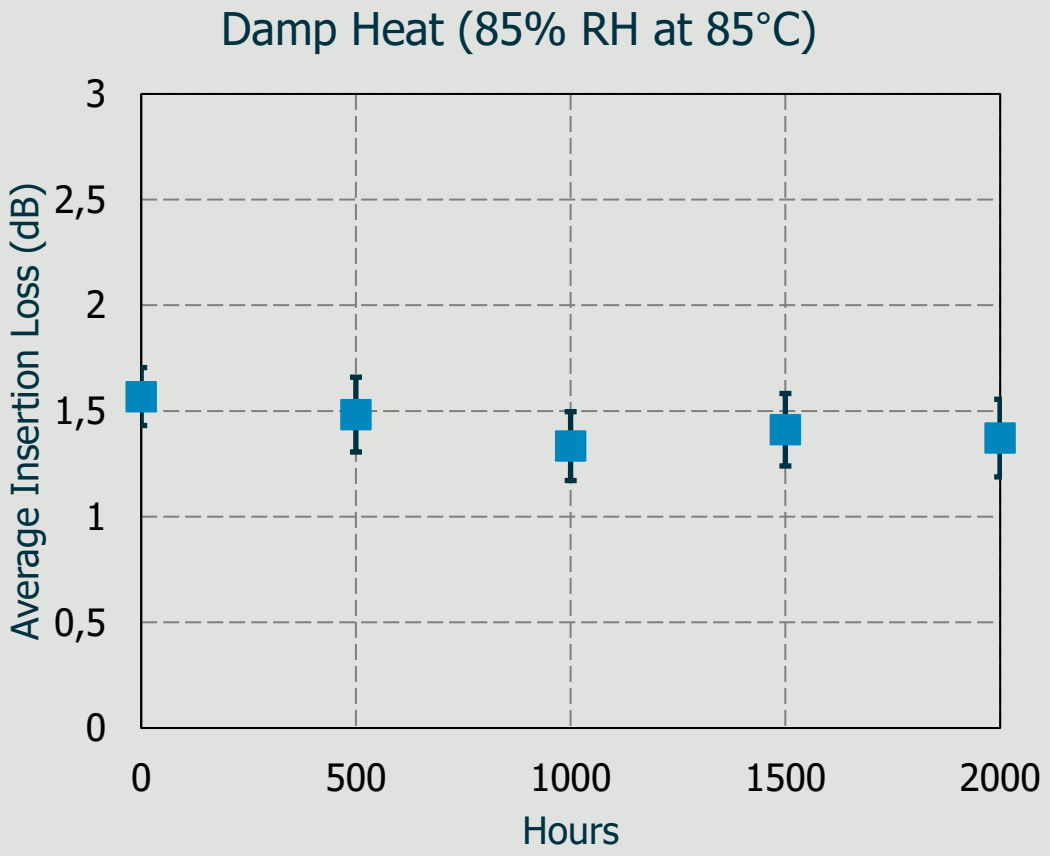
- **~1.7dB loss**

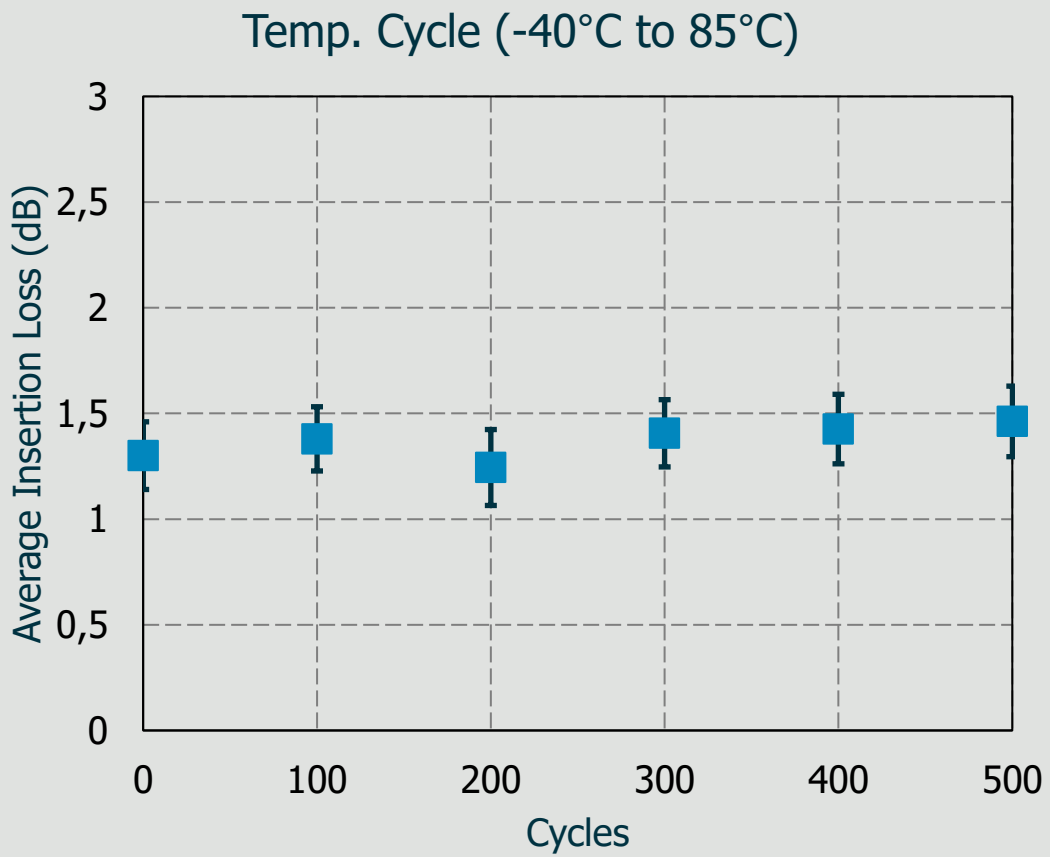




ON
MYCRONIC

Reliability - Insertion Loss in Damp Heat and Temperature Cycling





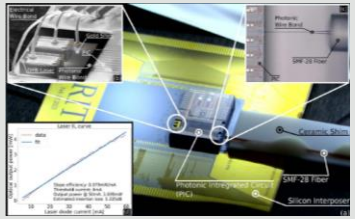
vanguard AUTOMATION
MYCRONIC

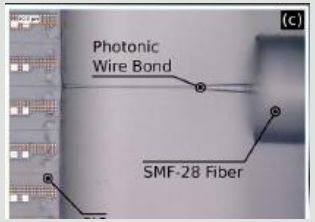
Use Cases – Photonic Wire Bonding

Active Device Integration

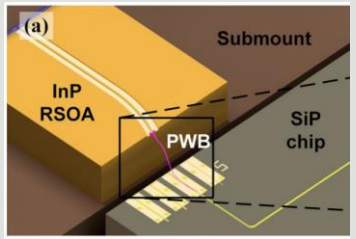
Multi-Chip Hybrid Integration | Passive alignment process | Mode-field-matching | Relaxed pick and place tolerances of ± 30 µm

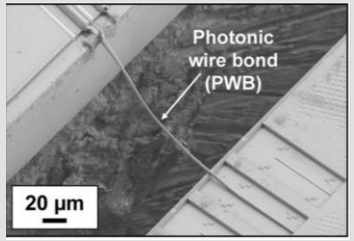
"Packaged Tunable Single-Mode III-V Laser Integrated on a Silicon Photonic Integrated Chip Using Photonic Wire Bonding",(2024) Deenadayalan et al., IEEE 74th (ECTC), Denver, Colorado, USA)



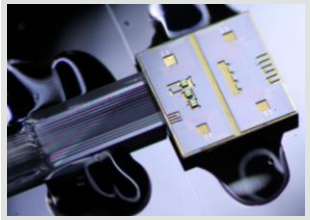


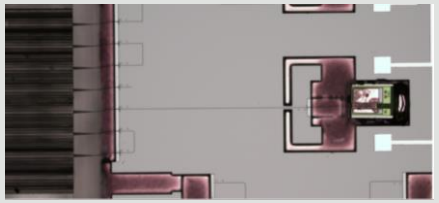
"Hybrid external-cavity lasers (ECL) using photonic wire bonds as coupling elements ",(2021)
Xu et al., Sci Rep 11, Article Number 16426 (2021)





"SiEPICfab: the Canadian silicon photonics rapid-prototyping foundry for integrated optics and quantum computing",(2021)
Darcie et al. , Proc. SPIE 11691, Silicon Photonics XVI

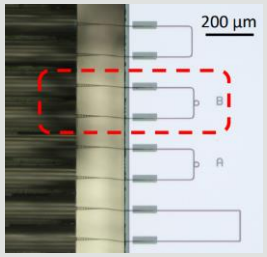


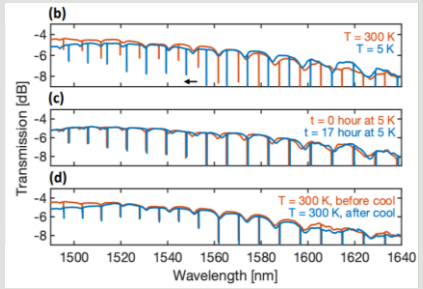


Quantum Applications

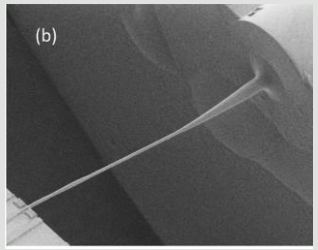
Cryogenic temperatures | (IL) < 2dB | No degradation

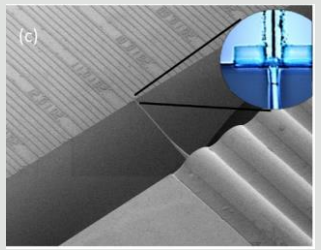
"Cryogenic Optical Packaging Using Photonic Wire Bonds", (2023)
arXiv:2307.07496v1 [physics.optics]





"Plug-and-Play Fiber-Coupled Quantum Dot Single-Photon Source via Photonic Wire Bonding", Adv Quantum Technol. 2023, 2300227





Micro-Optical Elements for **industrial** applications

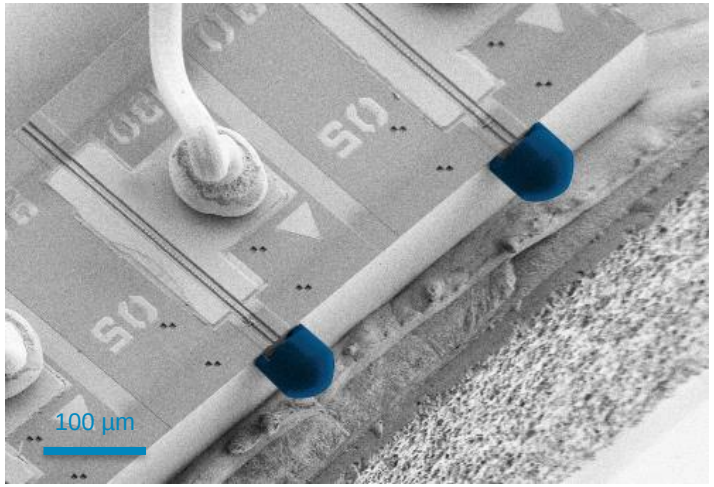
Compatible components
- Laser (DFB and other)
- PIN and APD diodes
- SMF, PMF and MMF fiber arrays
- PIC: SOI, SiN, InP, LiNb and more

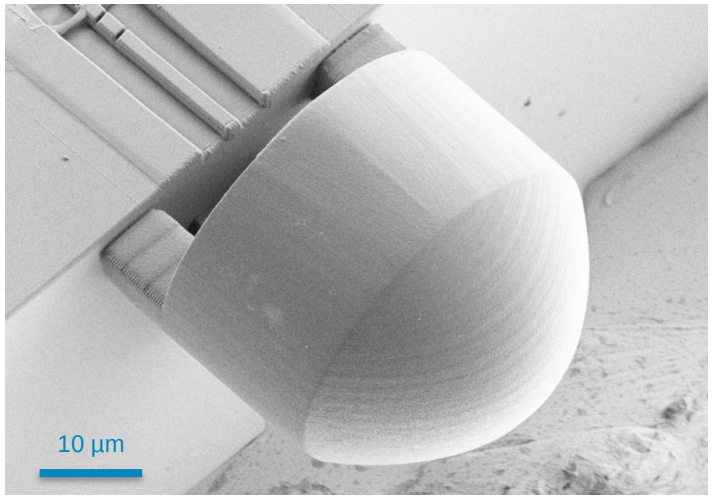
Standard building blocks:
- Lenses with focal length up to centimeters and mode-field diameters of 2.0 µm to 100 µm (@1/e² intensity)
- Total-internal-reflection mirrors
- 3D-printed mode-size converter

Coupling, depending on laser and chip
- Laser-to-Chip: 0.6 to 2.5 dB
- Chip-to-Fiber: 1.5 to 2.5 dB

Alignment tolerances @ 1 dB penalty:
- ±1.5 µm (single lens on one component) to ±15 µm (beam expander)

Tested operational range
- 530 nm to 2000 nm





Reproducibility
- Below σ = 0.2 dB coupling variation
- Below 10% mode-field and focus length variation/deviation

Accuracy
- Below σ = 50 nm detection accuracy
- Below ±100 nm shape accuracy
- Less than 10 nm RMS-roughness

Reliability testing
- > 4000 h 85°C/85% rel. hum
- > 250 cycles -40°C to 85°C
- Reflow soldering, 3 cycles, 270°C
- Die bonding, 310°C

Shock testing
- Acceleration of up to 1500 g
- Vibration, 20g, all axis

High power operation
- >1 W @ 1550 nm

Cryogenic operation
- > 10 cycles 4K to room temperature

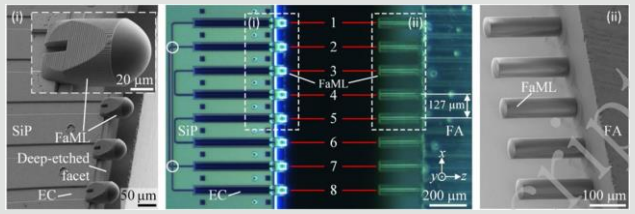
vanguard AUTOMATION
MYCRONIC

Use Cases – 3D-printed lenses

Relaxed Alignment Tolerances | Maximize Coupling Efficiency | Low Back reflectance

"3D-printed facet-attached microlenses for advanced photonic system assembly",(2023)
Xu et al., 2023. Light: Advanced Manufacturing, 4 (3). doi:10.37188/lam.2023.003

Alignment tolerance ± 14.4 µm with a 1 dB penalty

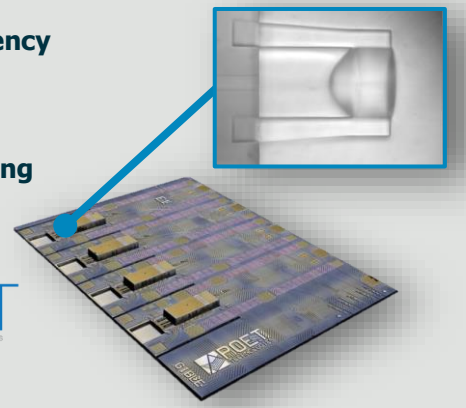


Collaboration to incorporate 3D-lithography technology into POET's Optical Interposer™ platform.

Increased Efficiency

Cost Reduction

Wafer level scaling

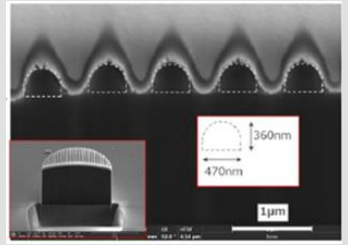


"3D-printed aspherical lens with moth-eye anti-reflection structure",(2024)
Y. Mizuno et al., Proc. SPIE 12898, Advanced Fabrication Technologies for Micro/Nano Optics and Photonics XVII, 128980R

Reflectance on the lens surface was reduced to **0.005%**

Coupling efficiency to fiber is improved to **-0.33 dB**

Structure size 360 x 470 nm



Connect with Innovation

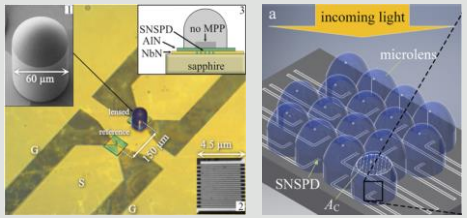
Quantum Applications

Cryogenic temperatures | No degradation | Broadband working range 530 – 2000 nm

"Superconducting nanowire single-photon detector with 3D-printed free-form microlenses", Opt. Express 29, 27708-27731 (2021)

The paper demonstrates FaMLs operating at **cryogenic temperatures** down to **4.6K**

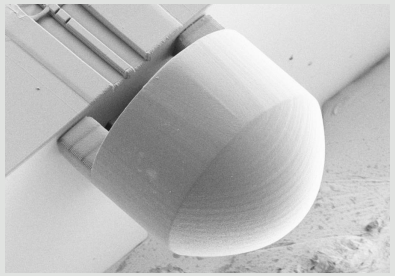
Assemblies undergo **10 cool down cycles**



Path to Implement Photonic Integration with 3D Lithography

Step 1- 3D printed elements

3D printed elements



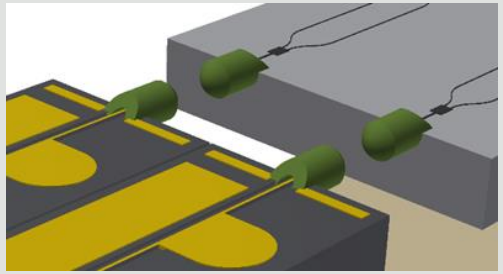
+

Active alignment

- improve coupling and yield
- No major changes to production process steps

Step 2- passive alignment

FaML



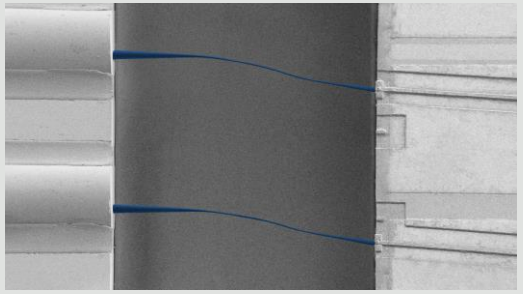
+

Passive alignment (±15µm)

- passive assembly is a viable process

Step 3- PWBs with relaxed alignment tolerances

PWBs



+

Relaxed Pick & Place (±30µm)

- ensuring compact coupling
- high yields
- high package density

vanguard AUTOMATION

MYCRONIC

Vanguard **SYMPHONY 1000**

Machines

SONATA 1000

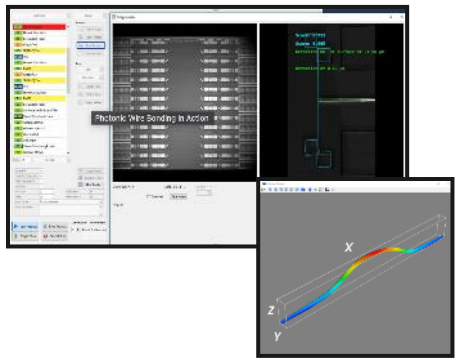
Automated 3D Lithography-based Nano Printing

REPRISE 1000

Automated Pre- and Post-Processing: Development and Encapsulation

Software

Composer and BrightWire3D



Software for Machine Control, Process Development and Management

Additional Products and Services

VanCore, VanClad, …

Materials for the Production of PWBs and Micro Optical Lenses

Professional Services

- Training
- Process Development
- Feasibility Studies
- Development Support
- Maintenance Services

The Full Suite: SYMPHONY 1000

“Photonic integration and packaging with Photonic Wire Bonding and facet-attached micro-optical elements”, PIC Magazine, September 2023

“As PIC Production Ramps Up, Fabricator Eye Alignment Options”, Photonics Spectra, June 2022

“Photonic Wire Bonding: Using Lasers to Integrate Lasers”, Photonics Spectra, August 2022

“Integrated photonics for quantum applications”, Laser Focus World, September 2022

vanguard AUTOMATION

MYCRONIC

Ecosystem Partners, Academic and Industrial Users